



Product Information Sheet

EPO-TEK® E2036

Date: July 2019
Rev: VI
No. of Components: Two
Mix Ratio by Weight: 3 : 1
Specific Gravity: Part A: 2.81 Part B: 3.52
Pot Life: 3.5 Days
Shelf Life- Bulk: One year at room temperature
Shelf Life- Syringe: Six months at -40°C

Recommended Cure: 150°C / 1 Hour

Minimum Alternative Cure(s):
May not achieve performance properties listed below
 150°C / 30 Minutes
 125°C / 1 Hour

NOTES:

- Container(s) should be kept closed when not in use.
- Filled systems should be stirred thoroughly before mixing and prior to use.
- Performance properties (rheology, conductivity, others) of the product may vary from those stated on the data sheet when bi-pak/syringe packaging or post-processing of any kind is performed. Epoxy's warranties shall not apply to any products that have been reprocessed or repackaged from Epoxy's delivered status/container into any other containers of any kind, including but not limited to syringes, bi-paks, cartridges, pouches, tubes, capsules, films or other packages.

Product Description: A two component, slightly flexible, silver-filled, electrically conductive adhesive for semiconductor and electronic assemblies. It is a low Tg epoxy, intended for many kinds of electronics at the PCB level, flex circuitry, or optical devices. It can be used for resisting thermal cycles, high vibration applications or resisting PCB drop tests.

Typical Properties: Cure condition: 150°C / 1 Hour Different batches, conditions & applications yield differing results.
 Data below is not guaranteed. To be used as a guide only, not as a specification. * denotes test on lot acceptance basis

PHYSICAL PROPERTIES:			
* Color (before cure):	Part A: Silver	Part B: Silver	
* Consistency:	Soft, smooth paste		
* Viscosity (23°C) @ 20 rpm:	10,000-20,000	cPs	
Thixotropic Index:	4.0		
* Glass Transition Temp:	≥ 30 °C (Dynamic Cure: 20-200°C/ISO 25 Min; Ramp -10-200°C @20°C/Min)		
Coefficient of Thermal Expansion (CTE):			
	Below Tg:	39 x 10 ⁻⁶ in/in°C	
	Above Tg:	178 x 10 ⁻⁶ in/in°C	
Shore D Hardness:	75		
Lap Shear @ 23°C:	1,492	psi	
Die Shear @ 23°C:	≥ 5	Kg	1,778 psi
Degradation Temp:	444 °C		
Weight Loss:			
	@ 200°C:	0.13	%
	@ 250°C:	0.32	%
	@ 300°C:	0.65	%
Suggested Operating Temperature:	< 350 °C (Intermittent)		
Storage Modulus:	638,334 psi		
Ion Content:			
	Cl ⁻ :	422 ppm	Na ⁺ : 1 ppm
	NH ₄ ⁺ :	159 ppm	K ⁺ : 8 ppm
* Particle Size:			
	≤ 20 microns		

ELECTRICAL AND THERMAL PROPERTIES:		
Thermal Conductivity:	1.5	W/mK
* Volume Resistivity @ 23°C:	≤ 0.0003	Ohm-cm

This information is based on data and tests believed to be accurate. Epoxy Technology, Inc. makes no warranties (expressed or implied) as to its accuracy and assumes no liability in connection with any use of this product.